

SCHMID's Vertical Processing Line Outperforms Standard Solutions for Ultra-Thin Cores

- Homogeneous process results by symmetric chemical treatment on both sides
- Integrated contact-free inline clamping transport for ultra-thin core down to 25µm thickness
- Fine line etching capability down to 25µm lines and spaces
- Panel sampling in Zhuhai Technology Center

SCHMID has foreseen the PCB market's growing need for high accuracy etching and handling solutions facing ever decreasing line width and spacing as well as panel thickness down to 25µm. The development team in Zhuhai has thought outside the box and worked diligently to present the **Vertical DES Line** (Developing/Etching/Stripping) that meets current market requirements and outperforms any competitors.

Besides the whole DES line, SCHMID also provides vertical stand-alone machines for developing, etching and stripping as well as for flash etch processing, soldermask developing and precleaning.

Vertical processing has many considerable advantages such as less footprint compared to horizontal lines, a service-friendly design and full inline automation. Most notably vertical processing allows a double-sided symmetric chemistry treatment by identical process conditions on both sides of the substrate. This is especially beneficial in etching: by using a special chemistry that only is effective when hitting the substrate, the process result is absolutely homogeneous and the well-known puddling effect that occurs in horizontal etching is completely eliminated. Still up to today elaborate intermittent spraying techniques are necessary in trying to compensate this puddling effect.

Furthermore, the contact-free clamping transport perfectly protects ultra-fine lines during the fine line etching process. These lines could be damaged or peeled off in standard horizontal conveyor processing by minimum oscillation of the conveyor system or by any roller contact. Therefore SCHMID offers clamping systems already for its horizontal lines. Contact-free handling without human intervention pays off in substantial yield increase.

SCHMID has offers multiple vertical and also horizontal clamping systems for a wide range of panel sizes because of the flexible lengths that are possible in running direction. Panel sizes are only limited in width.

SCHMID welcomes you to the Zhuhai Technology Center for presenting the Vertical Etcher and providing panel sampling!

Picture Name: Vertical Etcher

Vertical Etcher at Zhuhai Technology Center

Number of characters (including spaces): 2419

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迅得集团的垂直生产线的超薄板制程在性能方面优于传统标准生产线

- 1) 享有两侧对称化学处理的同质制程
- 2) 无接触式运输系统能处理低至 25 微米的超薄板
- 3) 线阔和线距的蚀刻能力低至 25 微米

迅得集团已经预见到印刷电路板市场对于高精度度蚀刻的需求，且有了解决不断降低的线阔及厚度低至 25 微米面板的蚀刻方案。珠海的开发团队独树一帜，用心制作出垂直 DES 生产线，不仅满足了目前市场上的需求，且令我们的竞争对手望尘莫及。除了提供整条 DES 生产线外，迅得还备有独立的垂直生产线，如显影，蚀刻，退膜，此外，还有快速蚀刻处理，阻焊层显影和预清洁处理制程。

垂直制程具有一些独到的优势，例如和水平生产线相比占地面积较少，易维修和全自动化。尤其是垂直制程能有效提供均称化学处理，特别有利于蚀刻制程，当使用特定化学药品时产出均等质量，消除人所共知的在水平线出现的水坑效应。直到现在，补偿式喷涂技术在消除这种水坑效应时仍是不可或缺的。不仅如此，无接触运输系统在蚀刻制程中充分保护了超薄板。在水平传输制程中，线阔可能遭受到传输系统的振动或滚轮接触而损害或者脱落。无接触系统带来了重大的质量提升。这种传输模式是迅得的发明，且适用于水平生产线。

迅得还提供多种垂直夹板运输系统，可以灵活调节以配合不同大小电路板的需要。

迅得集团欢迎您来珠海参观垂直蚀刻线和提供测试样品。

图片名：垂直蚀刻

珠海技术中心的垂直蚀刻线

字数（包括空格）:598

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